

HVL368CM

Variable Capacitance Diode for VCO

REJ03G0227-0100Z Rev.1.00 Apr 28, 2004

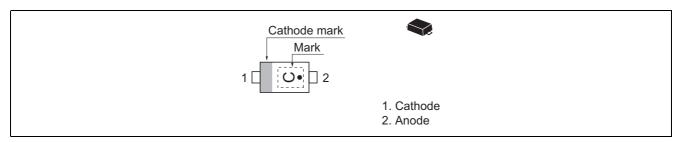
Features

- Narrow terminal Capacitance deviation.
- Low series resistance. $(r_s = 1.1 \Omega \text{ max})$
- Good C-V linearity.
- Thin Extremely small Flat Package (TEFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVL368CM	С	TEFP

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V_R	10	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	−55 to +125	°C

Electrical Characteristics

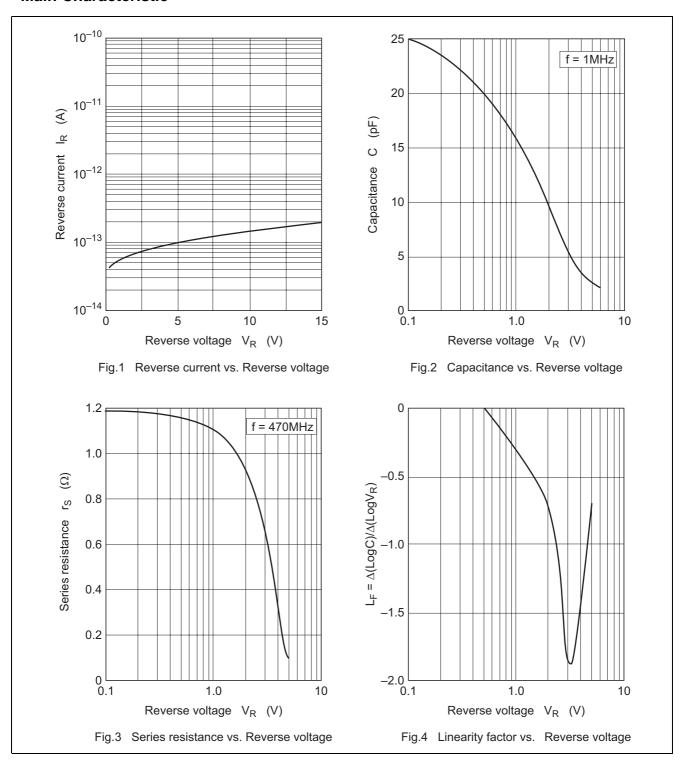
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	_	_	10	nA	V _R = 10 V
	I _{R2}	_	_	100		V _R = 10 V, Ta = 60°C
Capacitance	C ₁	15.0	_	16.5	pF	V _R = 1 V, f = 1 MHz
	C ₂	9.0		10.2		$V_R = 2 V$, $f = 1 MHz$
	C ₃	5.0	_	6.0		V _R = 3 V, f = 1 MHz
Capacitance ratio	n	2.2	_	_	_	C ₁ / C ₃
Series resistance	r _S	_	_	1.1	Ω	V _R = 2 V, f = 470 MHz

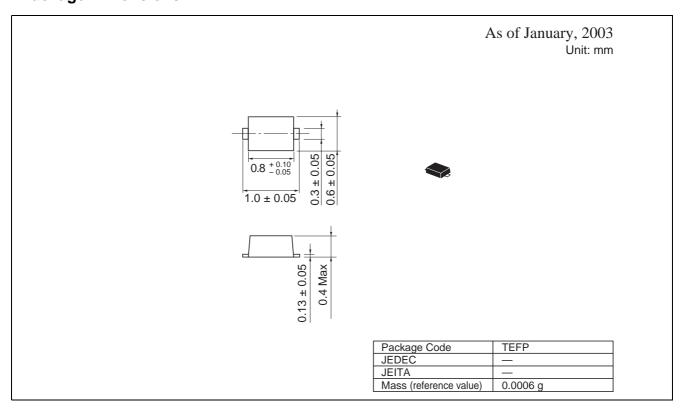
Notes: 1. Please do not use the soldering iron due to avoid high stress to the TEFP package.

^{2.} The material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic



Package Dimensions



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